

# STTH200L06TV

# Turbo 2 ultrafast high voltage rectifier

### Features

- Ultrafast switching
- Low reverse current
- Low thermal resistance
- Reduces switching and conduction losses

## Description

The STTH200L06TV, which is using ST Turbo 2 600 V technology, is specially suited for use in switching power supplies, and industrial applications (such as welding), as rectification diode.

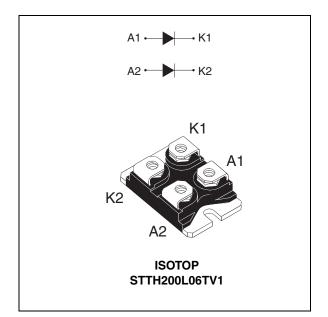


Table 1.Device summary

Symbol	Value			
I <sub>F(AV)</sub>	Up to 2 x 120 A			
V <sub>RRM</sub>	600 V			
Тj	150 °C			
V <sub>F</sub> (typ)	0.95 V			
t <sub>rr</sub> (max)	80 ns			

TM: ISOTOP is a trademark of STMicroelectronics

# 1 Characteristics

Table 2. Abs	olute ratings (limit	ting values, per diode)
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Symbol	Parameter		Value	Unit		
V <sub>RRM</sub>	Repetitive peak reverse voltage			600	V	
I <sub>F(RMS)</sub>	Forward rms current			180	А	
	Average forward current $\delta = 0.5$	T <sub>c</sub> = 65 °C	Per diode	100	А	
'F(AV)	$I_{F(AV)}$ Average forward current, $\delta = 0.5$	T <sub>c</sub> = 35 °C	Per diode	120	А	
I <sub>FSM</sub>	Surge non repetitive forward current	800	А			
T <sub>stg</sub>	Storage temperature range	-55 to + 150	°C			
Тj	Maximum operating junction temperatur	Maximum operating junction temperature				

### Table 3. Thermal parameter

Symbol	Parameter Maximum			
D	Junction to case	Per diode	0.60	
R <sub>th(j-c)</sub>	Sunction to case	Total	0.35	°C/W
R <sub>th(c)</sub>	Coupling		0.1	

When the diodes 1 and 2 are used simultaneously:

 $\Delta T_{j \text{ (diode1)}} = P_{\text{(diode1)}} \times R_{th(j-c) \text{ (per diode)}} + P_{\text{(diode2)}} \times R_{th(c)}$ 

Table 4.	Static electrical characte	eristics (per diode)	
	<b>-</b> .		

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I <sub>B</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>			100	μA
'R` ´	IR Preverse leakage current	T <sub>j</sub> = 125 °C	VR − VRRM		100	1000	μΛ
V <sub>F</sub> <sup>(2)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 100 A			1.55	V
		T <sub>j</sub> = 150 °C			0.95	1.20	v

1. Pulse test:  $t_p = 5 \text{ ms}, \delta < 2 \%$ 

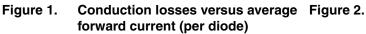
2. Pulse test:  $t_p = 380 \ \mu s, \ \delta < 2 \ \%$ 

To evaluate the maximum conduction losses use the following equation: P = 0.93 x  $I_{F(AV)}$  + 0.0027  ${I_F}^2_{(RMS)}$ 



Symbol	Parameter		Test conditions	Min.	Тур.	Max.	Unit
+	Reverse recovery	T <sub>i</sub> = 25 °C	$I_{F}$ = 0.5 A, $I_{rr}$ = 0.25 A, $I_{R}$ = 1 A			80	ns
t <sub>rr</sub>	time	1 <sub>j</sub> =25 C	$  I_F = 1 \text{ A}, \ \text{d}I_F/\text{d}t = 50 \text{ A}/\mu\text{s}, \\ V_R = 30 \text{ V} $		85	120	115
I <sub>RM</sub>	Reverse recovery current	T <sub>j</sub> = 125 °C	$I_{F} = 100 \text{ A}, dI_{F}/dt = 400 \text{ A}/\mu\text{s}, \\ dI_{F}/dt = 100 \text{ A}/\mu\text{s}$		15	20	А
t <sub>fr</sub>	Forward recovery time	T <sub>j</sub> = 25 °C	$I_F = 100 \text{ A, } dI_F/dt = 200 \text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \text{ x } V_{Fmax}$			700	ns
V <sub>FP</sub>	Forward recovery voltage	T <sub>j</sub> = 25 °C	$I_F = 100 \text{ A}, dI_F/dt = 200 \text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \text{ x } V_{Fmax}$		3.4		V

Table 5. Dynamic characteristics (per diode)



### Forward voltage drop versus forward current (per diode)

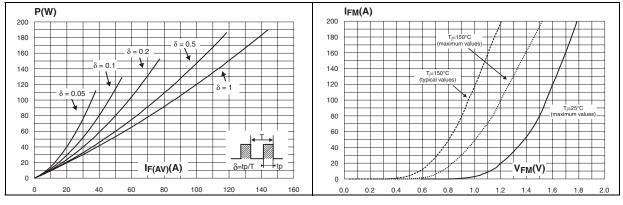
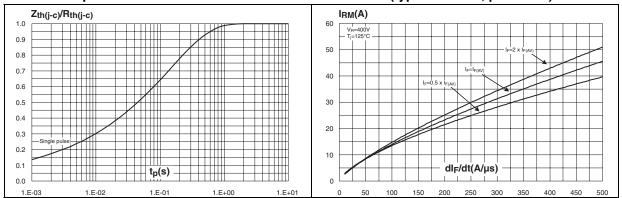


Figure 3. Relative variation of thermal impedance junction to case versus pulse duration

Figure 4. Peak reverse recovery current versus dl<sub>F</sub>/dt (typical values, per diode)

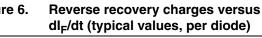


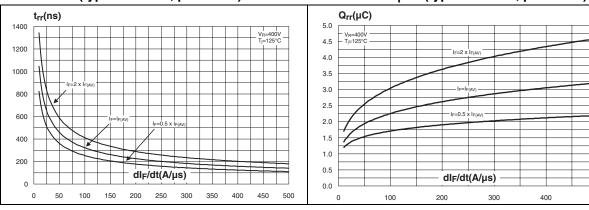


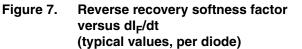
500

57

### Figure 5. Reverse recovery time versus dl<sub>F</sub>/dt Figure 6. (typical values, per diode)







**Relative variations of dynamic** Figure 8. parameters versus junction temperature

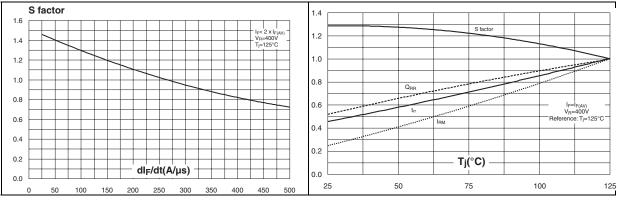
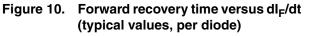
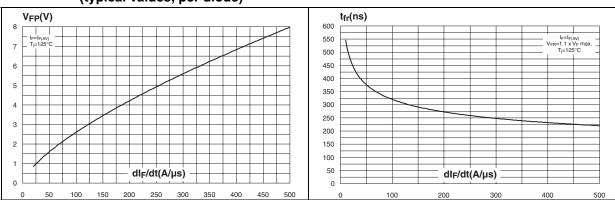


Figure 9. Transient peak forward voltage versus dI<sub>F</sub>/dt (typical values, per diode)





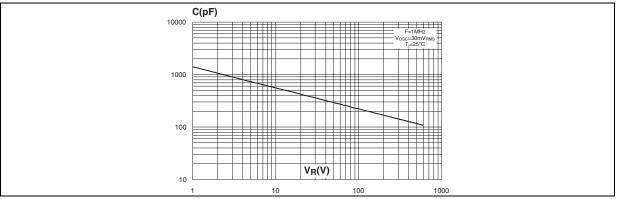


Figure 11. Junction capacitance versus reverse voltage applied (typical values, per diode)

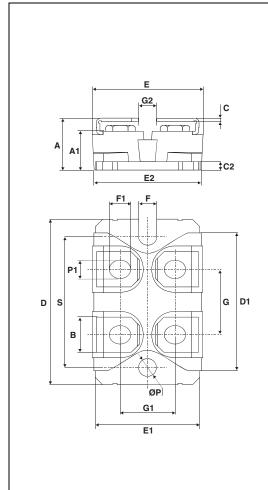


## 2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <u>www.st.com</u>. ECOPACK<sup>®</sup> is an ST trademark.

Table 6. ISOTOP dimensions



	Dimensions					
Ref.	Millim	neters	Inc	hes		
	Min.	Max.	Min.	Max.		
А	11.80	12.20	0.465	0.480		
A1	8.90	9.10	0.350	0.358		
В	7.8	8.20	0.307	0.323		
С	0.75	0.85	0.030	0.033		
C2	1.95	2.05	0.077	0.081		
D	37.80	38.20	1.488	1.504		
D1	31.50	31.70	1.240	1.248		
Е	25.15	25.50	0.990	1.004		
E1	23.85	24.15	0.939	0.951		
E2	24.80	0 typ.	0.97	6 typ.		
G	14.90	15.10	0.587	0.594		
G1	12.60	12.80	0.496	0.504		
G2	3.50	4.30	0.138	0.169		
F	4.10	4.30	0.161	0.169		
F1	4.60	5.00	0.181	0.197		
Р	4.00	4.30	0.157	0.69		
P1	4.00	4.40	0.157	0.173		
S	30.10	30.30	1.185	1.193		



# **3** Ordering information

### Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH200L06TV1	STTH200L06TV1	ISOTOP	27 g (without screws)	10 (with screws)	Tube

# 4 Revision history

### Table 8.Document revision history

Date	Revision	Changes
07-Sep-2004	1	First issue.
05-Sep-2011	2	Updated Figure 6.



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